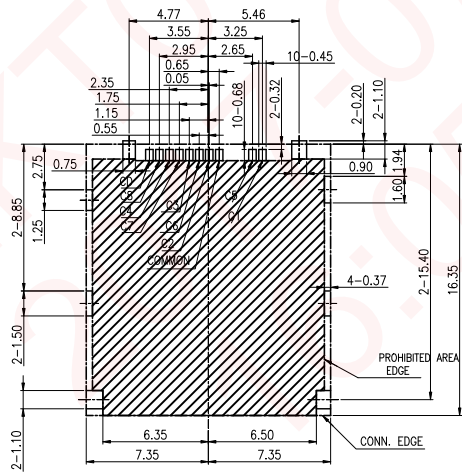


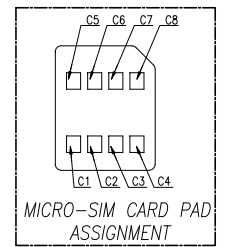
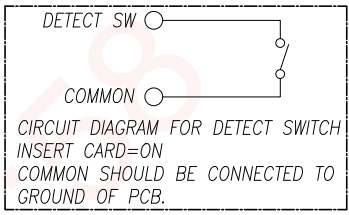
PIN NO.	PIN ASSIGNMENT
C1	SUPPLY VOLTAGE(VCC)
C2	RESET(RST)
C3	CLOCK(CLK)
C4	RESERVED FOR FUTURE USE(RFU)
C5	GROUND(GND)
C6	PROGRAMMING VOLTAGE(VPP)
C7	I/O
C8	RESERVED FOR FUTURE USE(RFU)



RECOMMENDED P.C.B. LAYOUT
 TOLERANCE (TOP VIEW) ±0.05mm
 □ SOLDER PAD
 ▨ NO PATTERN AND VIA HOLE IN ALLOW AREA

REV.	ECN NO. OR DESCRIPTION	REVISED	DATE
A	PRODUCT RELEASE	WZJ_Wei	2015.11.06
B	ECN: C170040, SPRING FORM MODIFICATION	WZJ_Wei	2017.06.27

- SPECIFICATIONS:
- ELECTRICAL CHARACTERISTICS:
 - CURRENT RATING: 1A.
 - DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR ONE MINUTE.
 - INSULATION RESISTANCE: 100MΩ MIN. BY 500V DC.
 - CONTACT RESISTANCE: 100mΩ MAX.(INITIAL)
 - LIFE TEST: 1500 CYCLES MIN.
 - OTHER GENERAL SPEC. TO REFER "2SM2019 SERIES SPEC".
 - TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
 - HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT: Ⓢ
 - HALOGEN FREE PRODUCT IDENTIFICATION LABEL ON PACKAGING: Ⓢ
 - FOR REFLOW SOLDERING LEAD-FREE PROCESS.
 - PACKAGING: TAPE & REEL.



F	LINK	1	STAINLESS STEEL	
E	SPRING	1	SWP	NICKEL PLATING OVER ALL
D	SLIDE	1	HIGH TEMP.THERMOPLASTIC,UL4V-0	BLACK
C	SHELL	1	STAINLESS STEEL,0.10T	NICKEL PLATING OVER ALL
B	CONTACT	1	COPPER ALLOY,0.10T	3u" GOLD PLATING ON CONTACT AREA AND SOLDER AREA 50u" MIN. NICKEL UNDER-PLATED.
A	HOUSING	1	HIGH TEMP. THERMOPLASTIC UL 94V-0	BLACK
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR

UNLESS OTHERWISE SPECIFIED TOLERANCES		Singatron Enterprise Co., Ltd. 信音企業股份有限公司	
DECIMALS:	ANGLES:	TITLE	MICRO-SIM CARD READER PUSH TYPE(H=1.25mm)
X :±0.5	X :±2°	DWN	Zhijun_Wei 17/07/04
X.X :±0.3	X.X :±1°	CHKD	Zhijun_Wei 17/07/04
X.XX :±0.2		APVD	WZJ_Wei 17/07/04
		PART NO.	2SM2019-000111F
		SCALE	5:1
		UNIT	mm
		SIZE	A3
		SHEET	1 OF 1
		REV	B

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